

# RSJ400N10

### Nch 100V 40A Power MOSFET

V <sub>DSS</sub>	100V
R <sub>DS(on)</sub> (Max.)	27mΩ
I <sub>D</sub>	±40A
P <sub>D</sub>	50W

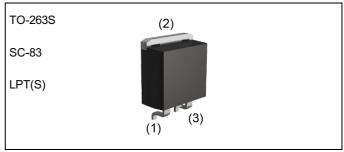
# ● Features

- 1) Low on-resistance
- 2) Fast switching speed
- 3) High power small mold package
- 4) Pb-free plating; RoHS compliant

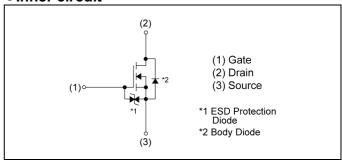
# Application

Switching

### Outline



### ●Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	330
Туре	Tape width (mm)	24
	Quantity (pcs)	1000
	Taping code	TL
	Marking	RSJ400N10

### ● **Absolute maximum ratings** (T<sub>a</sub> = 25°C ,unless otherwise specified)

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	100	V
Continuous drain current	I <sub>D</sub> *1	±40	Α
Pulsed drain current	I <sub>DP</sub> *2	±80	Α
Gate - Source voltage	V <sub>GSS</sub>	±20	V
Avalanche current, single pulse	I <sub>AS</sub> *3	10	Α
Avalanche energy, single pulse	E <sub>AS</sub> *3	73	mJ
Power dissipation	P <sub>D</sub> *1	50	W
Junction temperature	T <sub>j</sub>	150	°C
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

### ●Thermal resistance

Parameter	Cymahal	Values			1.1
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal resistance, junction - case	R <sub>thJC</sub> *1	-	1	2.5	°C/W

# ● Electrical characteristics (T<sub>a</sub> = 25°C)

Davamatav	Cymahal	Conditions	Values			l limit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 1mA	100	-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{j}}$	$\frac{\Delta V_{(BR)DSS}}{\Delta T_j} I_D = 1 \text{mA}$ referenced to 25°C		116.9	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1	μA	
Gate - Source leakage current	I <sub>GSS</sub>	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μΑ	
Gate threshold voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = 10V, I <sub>D</sub> = 1mA	1.0	-	2.5	V	
Gate threshold voltage temperature coefficient	$\frac{\Delta V_{GS(th)}}{\Delta T_{j}}$	I <sub>D</sub> = 1mA referenced to 25°C	-	-3.6	-	mV/°C	
Static drain - source	D *4	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	19	27	O	
on - state resistance	R <sub>DS(on)</sub> *4	V <sub>GS</sub> = 4V, I <sub>D</sub> = 20A	-	21	30	mΩ	
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	2.9	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  *4	V <sub>DS</sub> = 10V, I <sub>D</sub> = 20A	23	-	-	S	

<sup>\*1</sup>  $T_c$  =25°C, Limited only by maximum temperature allowed.

<sup>\*2</sup> Pw ≤ 10µs, Duty cycle ≤ 1%

<sup>\*3</sup> L  $\simeq$  1mH, V<sub>DD</sub> = 50V, R<sub>G</sub> = 25 $\Omega$ , Starting T<sub>j</sub> = 25 $^{\circ}$ C Fig.3-1,3-2

<sup>\*4</sup> Pulsed

# ●Electrical characteristics (T<sub>a</sub> = 25°C)

Daramatar	Cumahad	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	3600	-	_
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 25V	-	270	-	pF
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	1	180	1	
Turn - on delay time	t <sub>d(on)</sub> *4	$V_{DD} \simeq 50V, V_{GS} = 10V$	1	25	1	
Rise time	t <sub>r</sub> *4	I <sub>D</sub> = 20A	-	80	-	no
Turn - off delay time	t <sub>d(off)</sub> *4	$R_L \simeq 2.5\Omega$		205	1	ns
Fall time	t <sub>f</sub> *4	$R_G = 10\Omega$	-	250	-	

# • Gate charge characteristics $(T_a = 25^{\circ}C)$

	\ a	,				
Parameter	Symbol	Conditions		Values		Unit
raiametei	Symbol	Conditions	Min.	Тур.	Max.	Offic
Total gate charge	Qg*4	V <sub>DD</sub> ≃ 50V.	-	90	-	
Gate - Source charge	Q <sub>gs</sub> *4	$V_{DD} \approx 50V$ , $I_D = 40A$ ,	-	12	-	nC
Gate - Drain charge	Q <sub>gd</sub> *4	V <sub>GS</sub> = 10V	-	18	-	

# ● Body diode electrical characteristics (Source-Drain) (T<sub>a</sub> = 25°C)

Darameter	Symbol	Conditions	Values			l leit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Continuous forward current	I <sub>S</sub>	T = 25°C	-	-	40	Α
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	80	Α
Forward voltage	V <sub>SD</sub> *4	V <sub>GS</sub> = 0V, I <sub>S</sub> = 40A	-	-	1.5	V

Fig.1 Power Dissipation Derating Curve

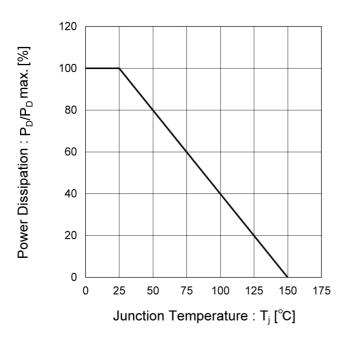
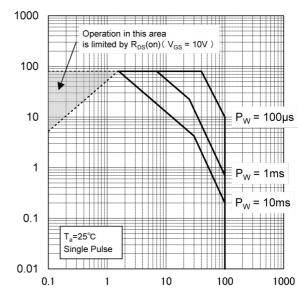


Fig.2 Maximum Safe Operating Area



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage: V<sub>DS</sub>[V]

Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

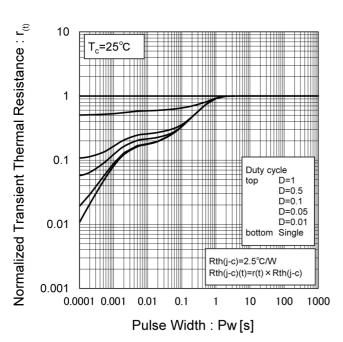


Fig.4 Single Pulse Maximum Power Dissipation

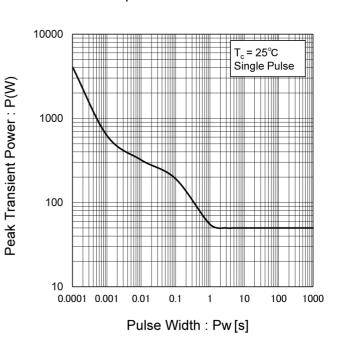


Fig.5 Typical Output Characteristics(I)

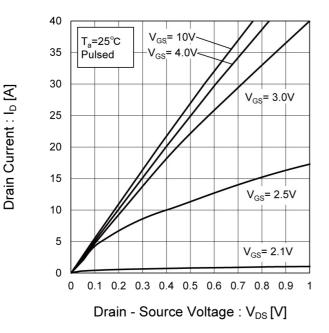
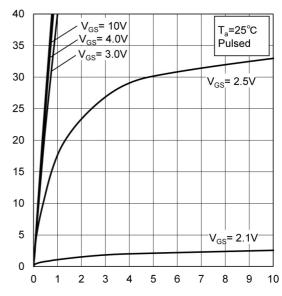


Fig.6 Typical Output Characteristics(II)



Drain Current : I<sub>D</sub> [A]

Drain - Source Voltage : V<sub>DS</sub> [V]

Fig.7 Breakdown Voltage vs.

Junction Temperature

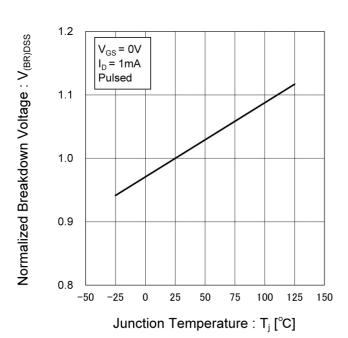


Fig.8 Typical Transfer Characteristics

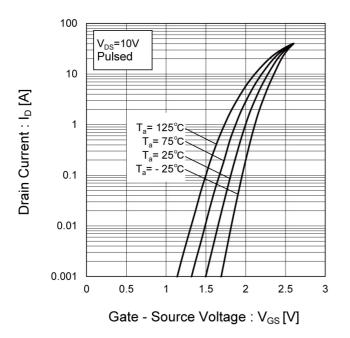


Fig.9 Gate Threshold Voltage vs.
Junction Temperature

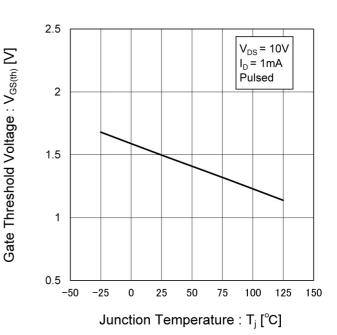


Fig.10 Forward Transfer Admittance vs.
Drain Current

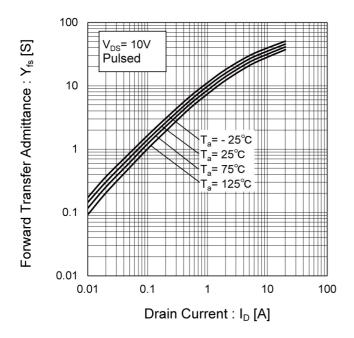


Fig.11 Drain Current Derating Curve

120 100 Drain Current Dissipation 80 : I<sub>D</sub>/I<sub>D</sub>max. [%] 60 40 20 0 0 25 50 75 100 125 150 Junction Temperature : T<sub>j</sub> [°C]

Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

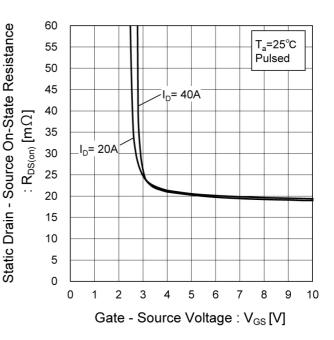


Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature

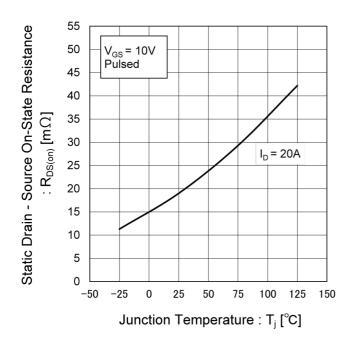


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I)

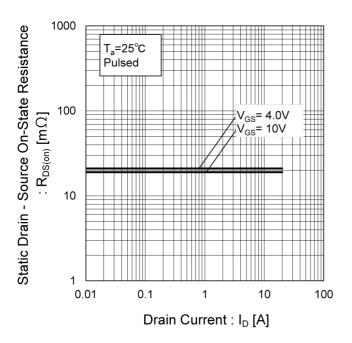


Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

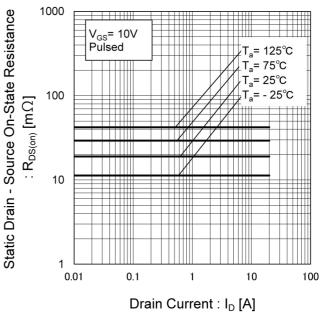


Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)

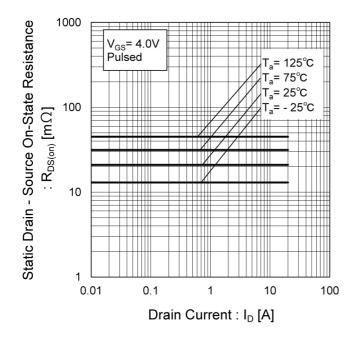


Fig.17 Typical Capacitances vs.

Drain - Source Voltage

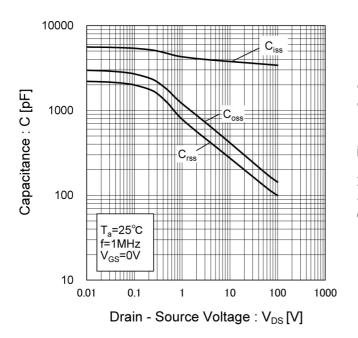


Fig.18 Switching Characteristics

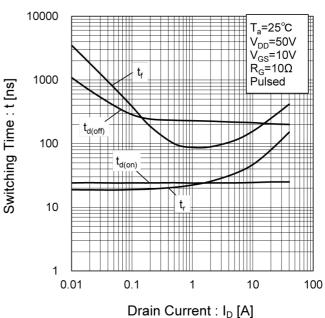


Fig.19 Typical Gate Charge

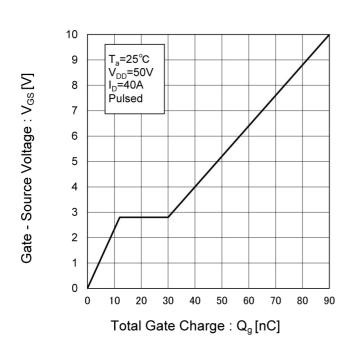
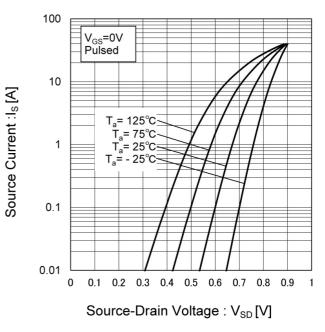


Fig.20 Source Current vs.

Source Drain Voltage



### Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

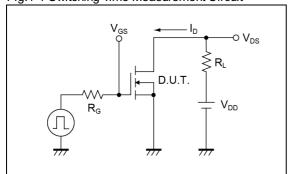


Fig.2-1 Gate Charge Measurement Circuit

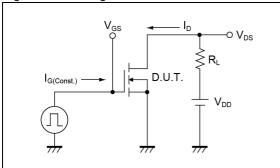


Fig.3-1 Avalanche Measurement Circuit

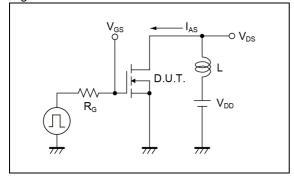


Fig.1-2 Switching Waveforms

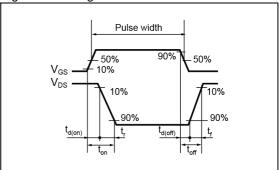


Fig.2-2 Gate Charge Waveform

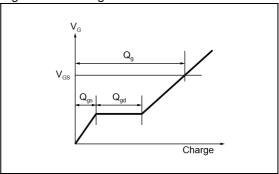
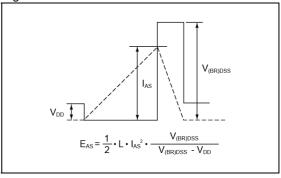
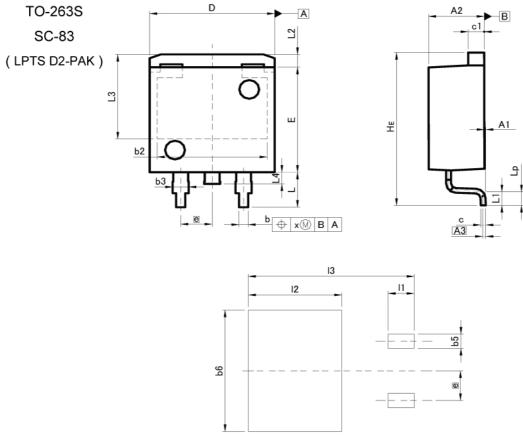


Fig.3-2 Avalanche Waveform



### Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM — A1 A2 A3	MILIMI MIN 0.00 4.30	MAX 0.30 4.70	MIN 0.000	MAX 0.012
A2	4.30			0.012
		4.70		0.012
Δ3	0	7.70	0.169	0.185
	0.3	25	0.0	10
b	0.68	0.98	0.027	0.039
b2	8.9	90	0.3	50
b3	1.14	1.44	0.045	0.057
С	0.30	0.60	0.012	0.024
c1	1.10	1.50	0.043	0.059
D	9.80	10.40	0.386	0.409
E	8.80	9.20	0.346	0.362
е	2.5	54	0.1	00
HE	12.80	13.40	0.504	0.528
L	2.70	3.30	0.106	0.130
L1	1.3	20	0.0	47
L2	1.1	10	0.043	
L3	7.:	25	0.285	
L4	1.0	00	0.0	39
Lp	0.90	1.50	0.035	0.059
X	-	0.25	-	0.010

DIM	MILIMETERS		INC	HES
DIM	MIN	MAX	MIN	MAX
b5	-	1.23	-	0.049
b6		10.40	-	0.409
- 11	_	2.10	-	0.083
12	-	7.55	i –	0.297
13	-2	13.40	-	0.528

Dimension in mm/inches



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JÁPAN	USA	EU	CHINA
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CLASSIV	CLASSⅢ	CLASSⅢ	CLASSⅢ

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  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
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- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
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- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
  may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
  exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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